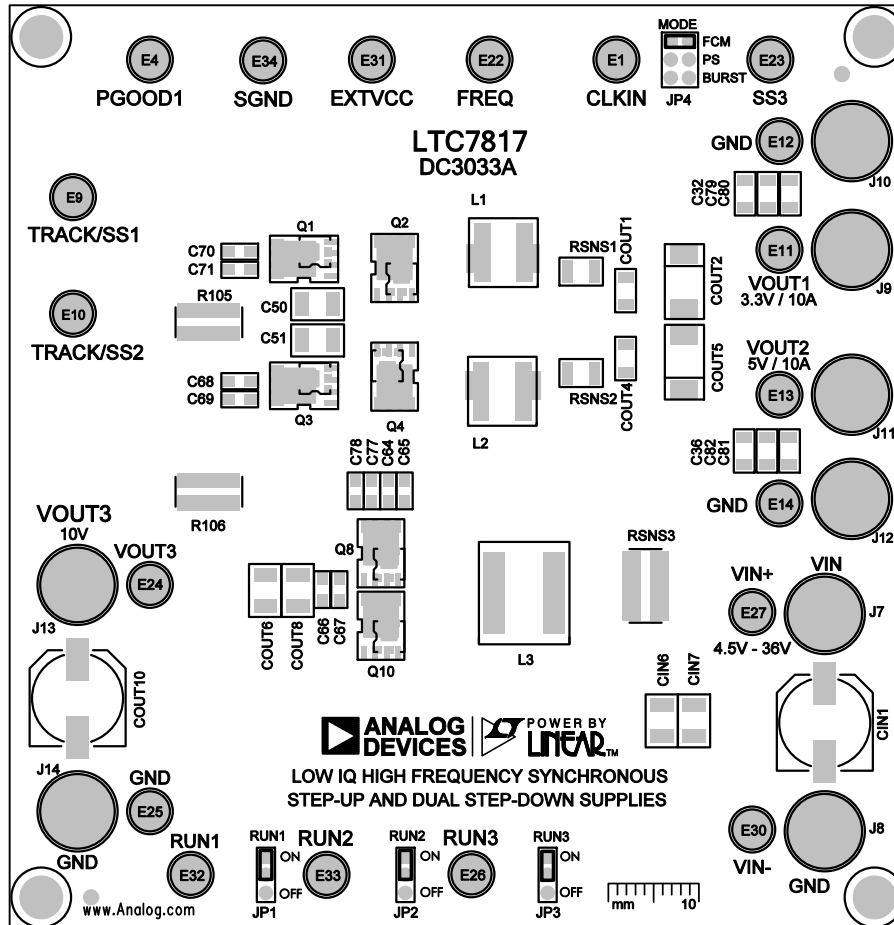
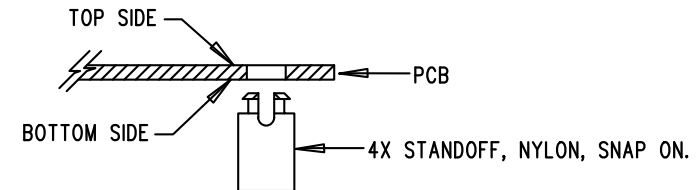


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	1	PROTOTYPE	LJ	10-14-19



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL STANDOFFS AS SHOWN BELOW:



APPROVALS		ANALOG DEVICES POWER BY LINEAR www.Analog.com FOR ADI CUSTOMER USE ONLY		
PCB DES.	LT	TITLE: TOP ASSEMBLY DRAWING LOW IQ HIGH FREQUENCY SYNCHRONOUS STEP-UP AND DUAL STEP-DOWN SUPPLIES		
APP ENG.	LJ			
		SIZE	IC NO.	REV.
		N/A	LTC7817EUHF DC3033A	1
SCALE = NONE		FILENAME: DC3033A-1.PCB		SHT 1 OF 2